

Appl. No. 10/650,505  
Supplemental Amdt. Dated July 13, 2005  
Reply to Office Action of June 3, 2005

Attorney Docket No. 81872.0051  
Customer No.: 26021

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Withdrawn) A dry etching apparatus, comprising:  
a chamber;  
an RF electrode provided inside said chamber; and  
a plate provided in parallel or nearly parallel with said RF electrode to cover a substrate to be etched, placed on said RF electrode directly or through a tray,  
wherein said plate is provided with a planar or nearly planar obstacle that inhibits a part of gas and plasma from passing through said plate.
2. (Withdrawn) The dry etching apparatus according to Claim 1, wherein a member forming said obstacle is provided with a number of opening portions.
3. (Withdrawn) The dry etching apparatus according to Claim 2, wherein an open area ratio of said obstacle is 5 to 40%.
4. (Withdrawn) The dry etching apparatus according to Claim 1, wherein said obstacle comprises a combination of a plurality of obstacle forming members, and an opening portion is provided between neighboring obstacle forming members.
5. (Withdrawn) The dry etching apparatus according to Claim 4, wherein an open area ratio of said obstacle is 5 to 40%.

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6. (Withdrawn) The dry etching apparatus according to Claim 1, wherein said obstacle comprises a plurality of long members aligned with a clearance in between.

7. (Withdrawn) The dry etching apparatus according to Claim 6, wherein said long member is a bar-shaped or sheet member.

8. (Withdrawn) The dry etching apparatus according to Claim 6, wherein said obstacle comprises a mesh woven by crossing said plurality of long members over and under with each other.

9. (Withdrawn) The dry etching apparatus according to Claim 1, wherein said obstacle comprises a plurality of obstacles of a laminated structure.

10. (Withdrawn) The dry etching apparatus according to Claim 9, wherein said obstacle comprises a member formed by laminating a plurality of long members aligned with a clearance in between, in different directions.

11. (Withdrawn) The dry etching apparatus according to Claim 1, wherein said obstacle is made of one kind or a combination of two or more kinds selected from a group consisting of materials (a), (b), and (c) as follows:

- (a) a glass-based material;
- (b) a metal material; and
- (c) a resin material.

12. (Withdrawn) The dry etching apparatus according to Claim 11, wherein said metal material is an aluminum-based material.

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13. (Original) A dry etching method for forming fine textures on a surface of a substrate to be etched, said dry etching method comprising:

placing a substrate to be etched on an RF electrode provided inside a chamber, directly or through a tray; and

covering said substrate to be etched with a plate,

wherein said plate is provided with a planar or nearly planar obstacle that inhibits a part of gas and plasma from passing through said plate.

14. (Currently amended) The dry etching method according to Claim 13, wherein said substrate to be etched is made of ~~any one of silicon, glass, metal, plastic, and resin.~~

15. (Original) The dry etching method according to Claim 13, wherein said plate covers said substrate to be etched while securing a distance of 5 mm to 30 mm.

16. (Withdrawn) A dry etching apparatus, comprising:  
a chamber;  
an RF electrode provided inside said chamber; and  
a plate provided with a number of opening portions and provided in parallel or nearly parallel with said RF electrode to cover a substrate to be etched, placed on said RF electrode directly or through a tray,  
wherein said plate is structured in such a manner that a surface and a back surface are reversed.

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17. (Withdrawn) The dry etching apparatus according to Claim 16, wherein the surface and the back surface of said plate are of substantially a same shape.

18. (Original) A dry etching method, comprising:  
placing a substrate to be etched on an RF electrode provided inside a chamber, directly or through a tray; and  
covering said substrate to be etched with a plate provided with a number of opening portions,  
wherein fine textures are formed on a surface of said substrate to be etched and said plate is cleaned on a surface side concurrently.

19. (Original) The dry etching method according to Claim 18, wherein said dry etching method is a reactive ion etching method.

20. (Original) The dry etching method according to Claim 18, wherein a substrate to be etched next is placed with a surface and a back surface of said plate being reversed after said plate is cleaned on the surface side, and fine textures are formed on a surface of said substrate to be etched next.

21. (Withdrawn) A cleaning method adopted in a dry etching apparatus for cleaning a surface of a plate, said cleaning method comprising:  
carrying out a substrate from a chamber;  
placing a plate provided with a number of opening portions inside said chamber; and  
introducing an etching gas inside said chamber.

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22. (New) The dry etching method according to Claim 13, wherein said substrate to be etched is made of any one of glass, metal, plastic, and resin.